

STX790A
Rev.E Mar.-2016

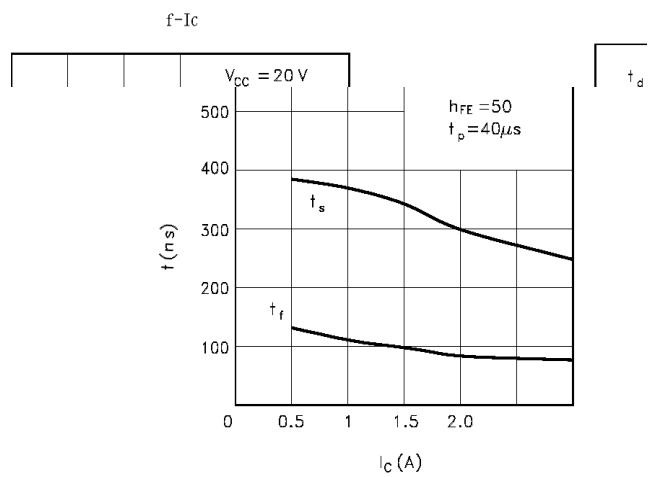
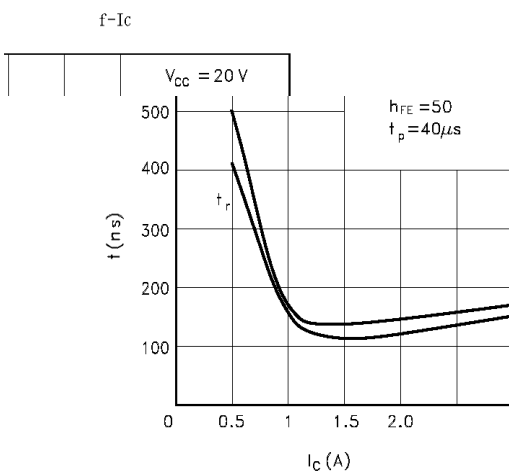
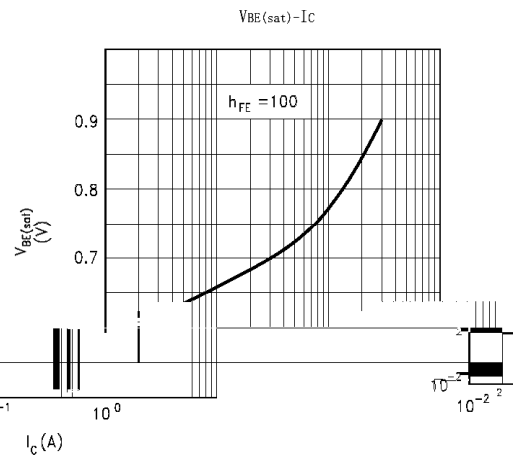
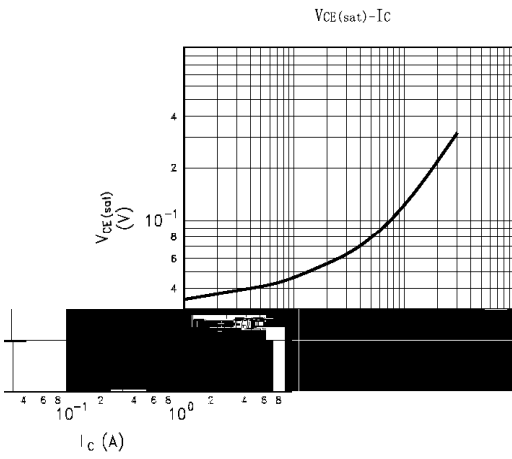
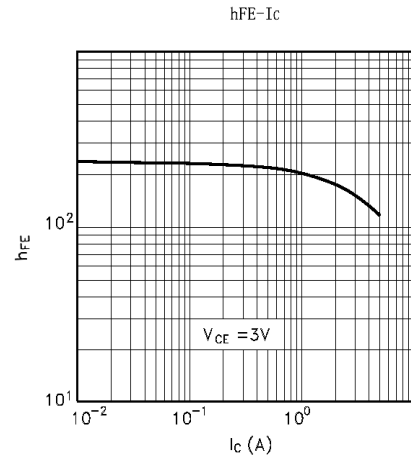
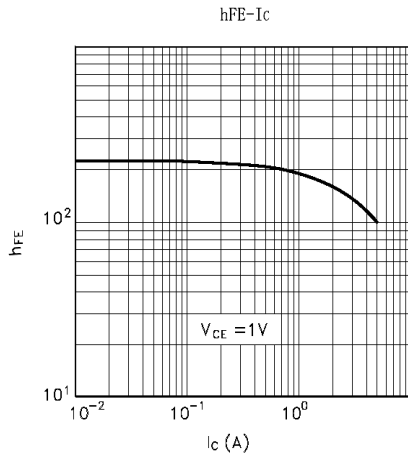
Silicon PNP transistor in a TO-92 Plastic Package.

High I_C ,low $V_{CE(sat)}$.

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-60	V
Collector to Emitter Voltage	V_{CEO}	-60	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-3.0	A
Peak Collector Current- Continuous	I_{CM}	-6.0	A
Collector Power Dissipation	P_C	0.9	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=-100\mu A$ $I_E=0$	-60			V
Collector to Emitter Breakdown Voltage*	* V_{CEO}	$I_C=-10mA$ $I_B=0$	-60			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E=-100\mu A$ $I_C=0$	-5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-30V$ $I_E=0$			-0.1	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=-4.0V$ $I_C=0$			-1.0	μA
DC Current Gain	* $h_{FE(1)}$	$V_{CE}=-2.0V$ $I_C=-500mA$	100	200	300	
	* $h_{FE(2)}$	$V_{CE}=-2.0V$ $I_C=-10mA$	100	200		
	* $h_{FE(3)}$	$V_{CE}=-1.0V$ $I_C=-3.0A$	90	130		
Collector to Emitter Saturation Voltage	* $V_{CE(sat)(1)}$	$I_C=-0.5A$ $I_B=-50mA$			-0.15	V
	* $V_{CE(sat)(2)}$	$I_C=-1.0A$ $I_B=-100mA$			-0.3	V
	* $V_{CE(sat)(3)}$	$I_C=-2.0A$ $I_B=-200mA$			-0.5	V
	* $V_{CE(sat)(4)}$	$I_C=-3.0A$ $I_B=-300mA$			-0.7	V
Base to Emitter Saturation Voltage*	* $V_{BE(sat)}$	$I_C=-1.0A$ $I_B=-100mA$		-0.8	-1.0	V
Base to Emitter Voltage	V_{BE}	$V_{CE}=-2.0V$ $I_C=-1.0A$		-0.8	-1.0	V

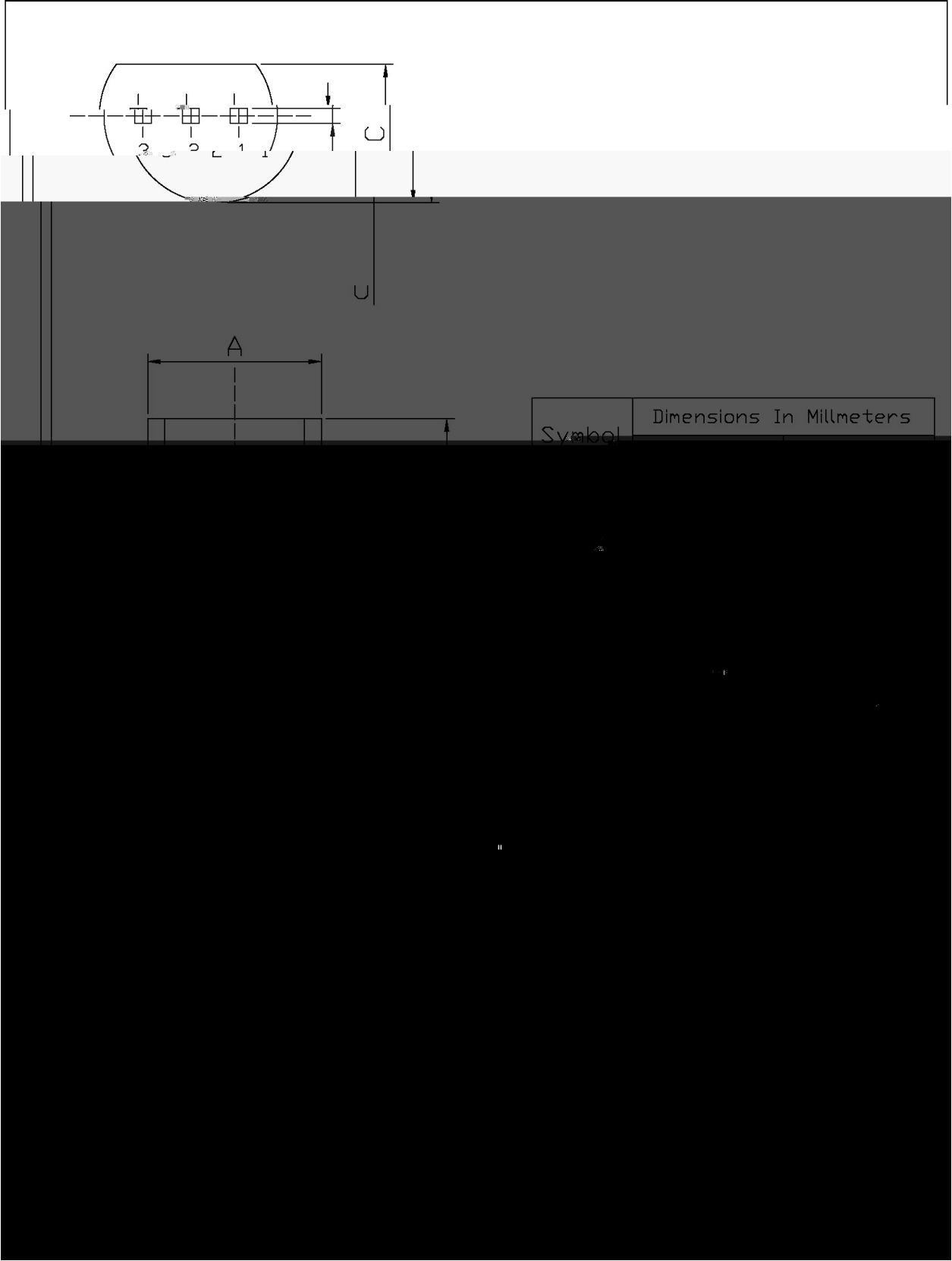
/ Electrical Characteristic Curve



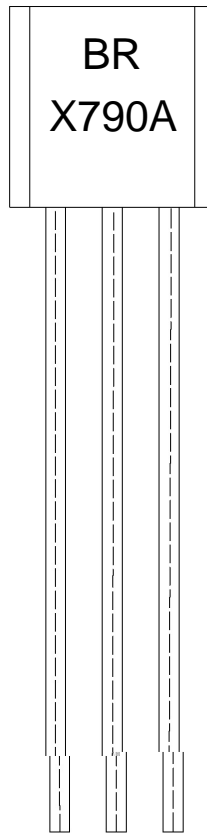
/ Package Dimensions

T0-92

Unit: mm



/ Marking Instructions



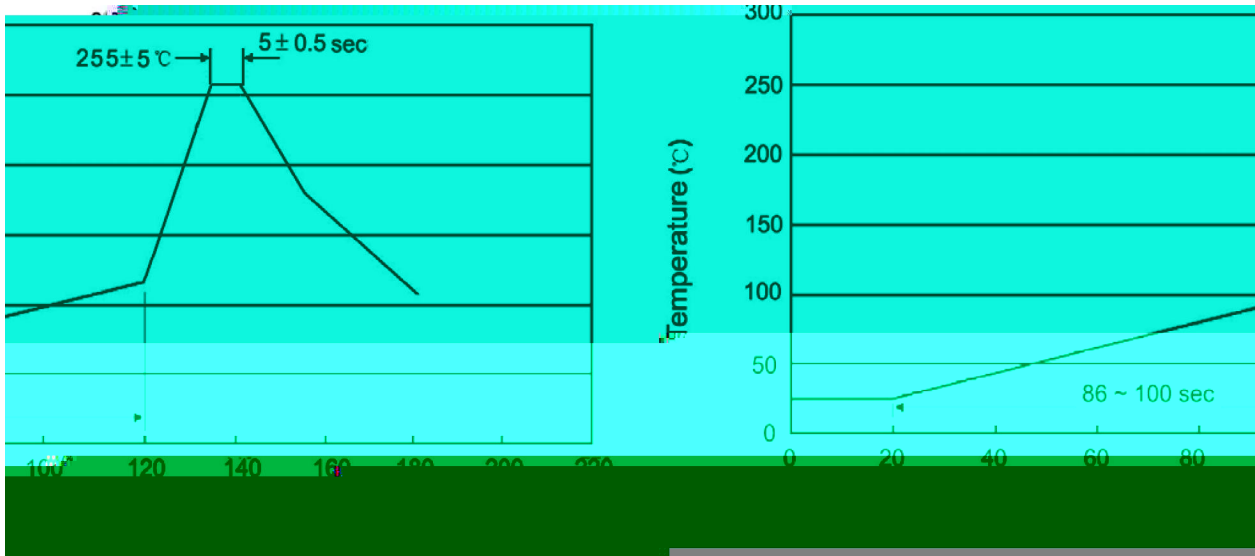
Note:

BR: Company Code.

X790A: Product Type.

****: Lot No. Code,code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|----------|-----------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255 | 5 | 5 | 0.5sec; | 2.Peak Temp.:255 5 , Duration:5 0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270 5 10 1 sec. Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱

/ AMMO

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)	
	只纸带	纸带盒	纸带层盒	盒箱	只箱	盒	箱
							小箱 大箱

/ Notices